



Broadcom Co-packaged Platform Solutions

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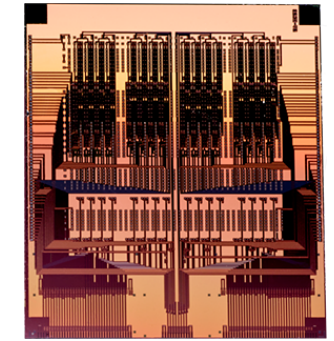
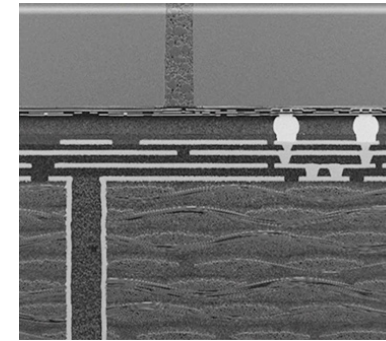
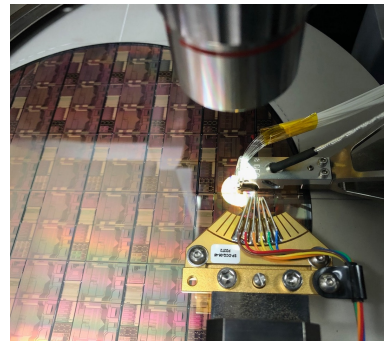
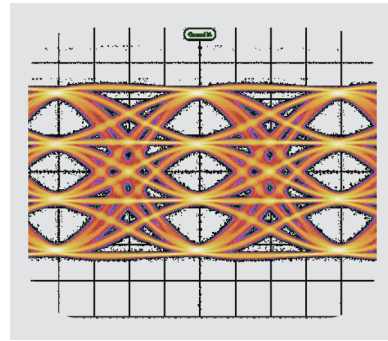


The last mile..



Opportunity for Step Function Improvement in Optical Connectivity

Broadcom's Unmatched Integration Capability Meets This Need



Switch Silicon

- Core switch, SerDes and DSP in leading node
- Sustained generational differentiation

Mixed Signal IC

- Power and performance optimized in both SiGe and CMOS

Optical Devices & Fabs

- 50M lasers/year from internal fabs
- High-volume optical manufacturing
- High-power, multi-wavelength sources

Advanced Packaging & Test

- Wafer-level test
- TSV
- 2.5D/3D integration

Silicon Photonics

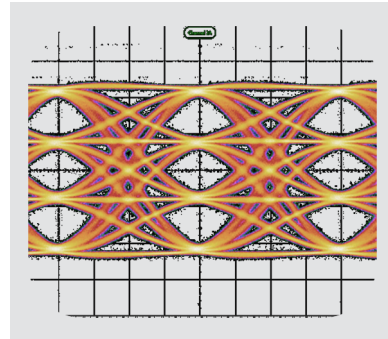
- High-density PIC design
- Modulators and PDs in silicon
- Low-loss SOI waveguides

Industry-Leading Economics, Volume, Power Efficiency at Scale

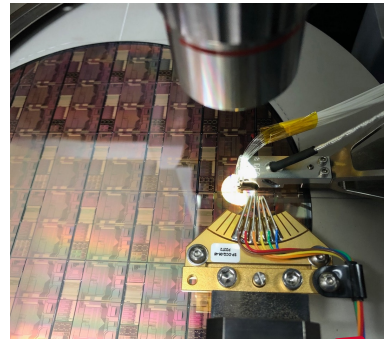
A Disruptive Silicon + Photonics Platform ...



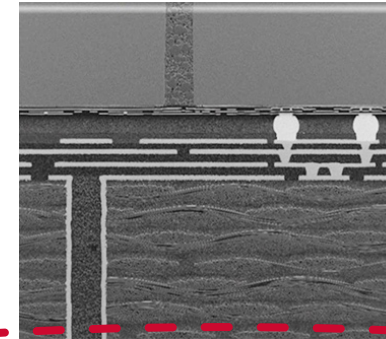
High Performance Silicon



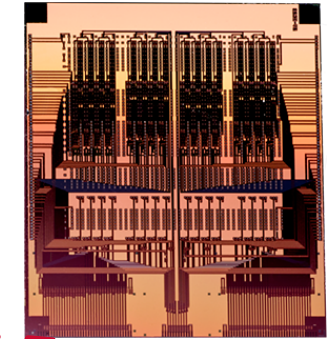
Mixed Signal IC



Optical Devices & Fabs



Advanced Packaging & Test

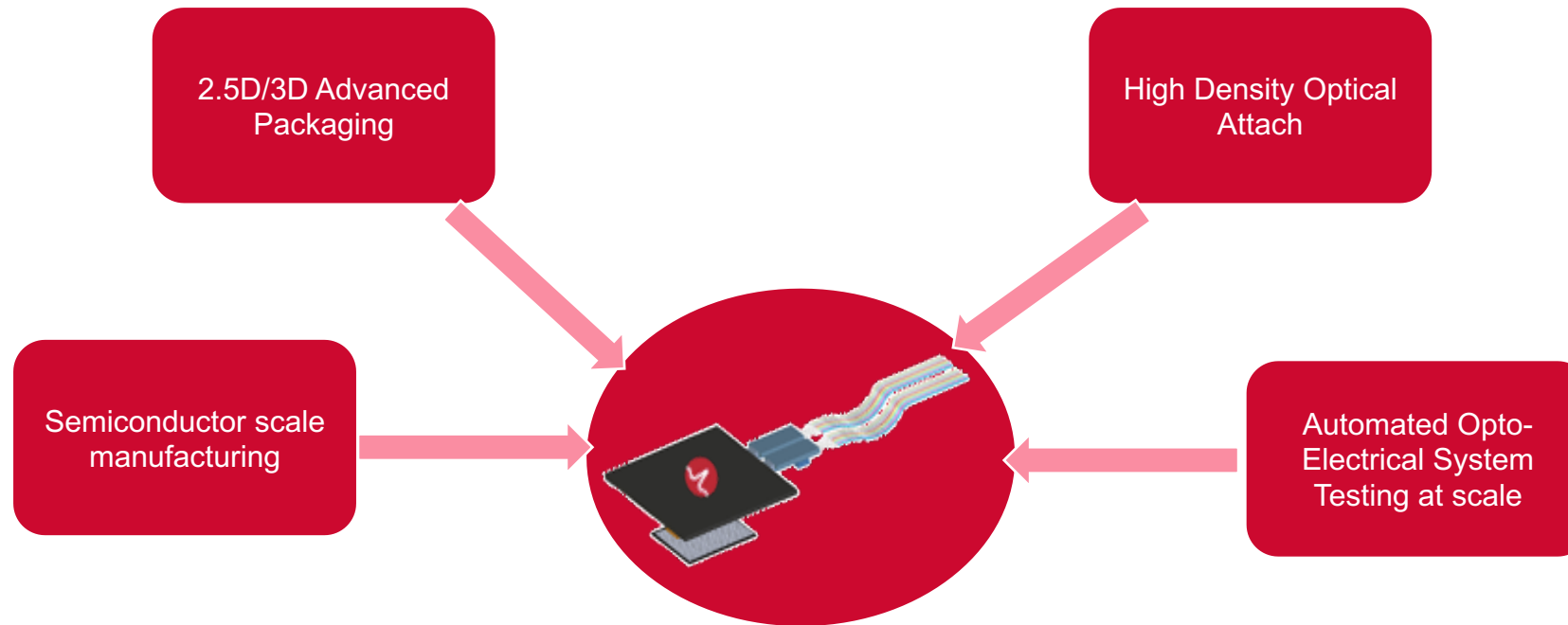


Silicon Photonics



Opportunity to Innovate

Challenges - Density, Volume & Economies of scale





BROADCOM®

connecting everything®